Datasheet: MakroPorP12S6-220



Macroporous silicon dead end pores on bulk silicon wafer (620515-W12)

Etching

Size: 6 inch

Pitch: 12 μm square

Pore length: 220 μm pore length (380 μm wafer thickness)

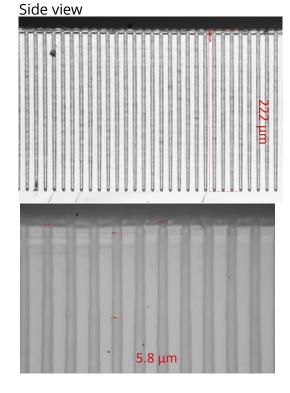
Shape: straight **Pore diameter:** 5-6 μm

Postprocessing

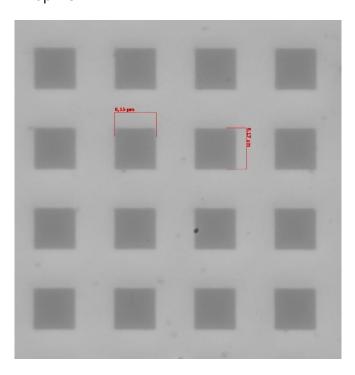
• Laser dicing 10 x 10 mm

Measurements

optical microscope



Top view



Please note: The wafer surface is prestructured with pyramidal pits prior to the photoelectrochemical pore formation process. Thus, optical microscopy from the front side does not show the real pore diameter.
